

PIC18F87K90 FAMILY

PIC18F87K90 Family Silicon Errata and Data Sheet Clarification

The PIC18F87K90 family devices that you have received conform functionally to the current Device Data Sheet (DS39957**D**), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in Table 1. The silicon issues are summarized in Table 2.

The errata described in this document will be addressed in future revisions of the PIC18F87K90 family silicon.

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated in the last column of Table 2 apply to the current silicon revision (B5, C6).

Data Sheet clarifications and corrections start on page 10, following the discussion of silicon issues.

The silicon revision level can be identified using the current version of MPLAB[®] IDE and Microchip's programmers, debuggers, and emulation tools, which are available at the Microchip corporate web site (www.microchip.com).

For example, to identify the silicon revision level using MPLAB IDE in conjunction with a hardware debugger:

- 1. Using the appropriate interface, connect the device to the hardware debugger.
- 2. Open an MPLAB IDE project.
- 3. Configure the MPLAB IDE project for the appropriate device and hardware debugger.
- 4. Based on the version of MPLAB IDE you are using, do one of the following:
 - a) For MPLAB IDE 8, select <u>Programmer ></u> <u>Reconnect</u>.
 - b) For MPLAB X IDE, select <u>Window ></u> <u>Dashboard</u> and click the Refresh Debug Tool Status icon ().
- 5. Depending on the development tool used, the part number *and* Device Revision ID value appear in the **Output** window.

The DEVREV values for the various PIC18F87K90 silicon revisions are shown in Table 1.

Part Number	Device	Revision ID for Silicon Revision ⁽²⁾								
Fart Number	ID ⁽¹⁾	A3	B1	B3	B5	C1	C3	C5	C6	
PIC18F65K90	524h									
PIC18F66K90	520h					106	11h	12h	13h	
PIC18F85K90	52Ah	3h	4h	5h	Ch	10h		1211	1311	
PIC18F86K90	526h	୍ଦ୍	40	on	6h					
PIC18F67K90	510h									
PIC18F87K90	514h									

TABLE 1: SILICON DEVREV VALUES

The Device IDs (DEVID and DEVREV) are located at the last two implemented addresses of Configuration memory space. They are shown in hexadecimal in the format "DEVID DEVREV".

1: Refer to the "PIC18F6XKXX/8XKXX Family Flash Microcontroller Programming Specification" (DS39947) for detailed information on Device and Revision IDs for your specific device.

Note: If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

TABLE 2:	SILICON ISSUE SUMMARY
----------	-----------------------

Module	Feature	ltem	Issue Summary		Af	fect	ed R	evis	ions	(1)	
Module	reature	Number	issue Summary	A3	B1	B 3	B5	C1	C3	C5	C6
Analog-to-Digital Converter (A/D)	A/D Offset	1.1	The 12-bit A/D performance is outside of the data sheet's A/D Converter specifications.	x							
Analog-to-Digital Converter (A/D)	A/D Offset	1.2	The 12-bit A/D performance is outside of the data sheet's A/D Converter specifications.		x	x	х	х	х	х	х
Ports	Leakage	2.	I/O port leakage is higher than the D060 spec in the data sheet.	х	х	х	х	х	х	х	х
High/Low-Voltage Detect (HLVD)	HLVD Trip	3.	The high-to-low (VDIRMAG = 0) setting of the HLVD may send initial interrupts.	x	x	x	x	x	x	х	x
ECCP	Auto-Shutdown	4.	The tri-state setting of the auto- shutdown feature in the enhanced PWM will not successfully drive the pin to tri-state.	x	x	x	x	х	x	х	x
EUSART	Synchronous Transmit	5.	When using the Synchronous Transmit mode, transmitted data may become corrupted if using the TXxIF bit to determine when to load the TXREGx register.	x	х	x	x	х	x	x	x
IPD and IDD	Maximum Limit	6.	Maximum current limits may be higher than specified in Section 31.2 "DC Characteristics: Power-Down and Supply Current PIC18F87K90 Family (Industrial)" of the data sheet.	x							
Ultra Low-Power Sleep	Sleep Entry	7.1	Entering Ultra Low-Power Sleep mode, by setting RETEN = 0 and SRETEN = 1, will cause the part not to be programmable through ICSP TM .	x	x			x			
Ultra Low-Power Sleep	WDT Wake-up	7.2	Using the WDT to exit Ultra Low- Power Sleep mode when VDD>4.5V can cause the part to enter a Reset state requiring POR to exit.	х	х	х	х	х	х	х	х
Resets (BOR)	Enable/ Disable	8.	An unexpected Reset may occur if the Brown-out Reset module (BOR) is disabled, and then re-enabled, when the High/Low-Voltage Detection module (HLVD) is not enabled (HLVDCON<4> = 0).	x	х	x	x	х	x	х	x
RG5 Pin	Leakage	9.	RG5 will cause excess pin leakage whenever it is driven low.		х						
Primary Oscillator	XT Mode	10.	XT Primary Oscillator mode does not reliably function when the driving crystals are above 3 MHz.	x	x	x		x	x		
Timer1/3/5/7	Interrupt	11.	When the timer is operated in Asynchronous External Input mode, unexpected interrupt flag generation may occur.	x	х	x		х	x	x	

Note 1: Only those issues indicated in the columns labeled B5 and C6 apply to the current silicon revision.

Silicon Errata Issues

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the shaded column in the following tables apply to the current silicon revision (**B5, C6**).

1. Module: Analog-to-Digital Converter (A/D)

1.1 The A/D will meet the Microchip standard A/D specification when used as a 10-bit A/D. When used as a 12-bit A/D, the possible issues include high offset error (up to a maximum of 50 LSBs), high DNL error (up to a maximum of ±4 LSBs) and multiple missing codes (up to a maximum of 20). Users should evaluate the 12-bit A/D performance in their application using the suggested work around below.

A/D Offset

The A/D may have high offset error, up to a maximum of 50 LSB; it can be used if the A/D is calibrated for the offset.

Work around

Method to Calibrate for Offset:

In Single-Ended mode, connect A/D +ve input to ground and take the A/D reading. This will be the offset of the device and can be used to compensate for the subsequent A/D readings on the actual inputs.

Affected Silicon Revisions

A1	B1	В3	B5	C1	C3	C5	C6	
Х								

1.2 The A/D will meet the Microchip standard A/D specification when used as a 10-bit A/D. When used as a 12-bit A/D, the possible issues include high offset error (up to a maximum of ±25 LSBs at 25°C, ±30 LSBs at 85°C, 125°C and -40°C), high DNL error (up to a maximum of ±4 LSBs) and multiple missing codes (up to a maximum of 20). Users should evaluate the 12-bit A/D performance in their application using the suggested work around below. See Table 3 for guidance specifications.

A/D Offset

The A/D may have high offset error, up to a maximum of ± 25 LSBs at 25°C, ± 30 LSBs at 85°C, 125°C and -40°C; it can be used if the A/D is calibrated for the offset.

Work around

Method to Calibrate for Offset:

In Single-Ended mode, connect A/D +ve input to ground and take the A/D reading. This will be the offset of the device and can be used to compensate for the subsequent A/D readings on the actual inputs.

Param. No.	Sym.	Characteristic	Min.	Тур.	Max.	Units	Conditions
A01	Nr	Resolution	_	_	12	bit	$\Delta V \text{Ref} \geq 5.0 V$
A03	EIL	Integral Linearity Error	_		±10.0	LSb	$\Delta VREF \ge 5.0V$
A04	Edl	Differential Linearity Error	—	_	+6.0/-4.0	LSb	$\Delta VREF \ge 5.0V$
A06	EOFF	Offset Error	—	_	±25	LSb	$\Delta VREF \ge 5.0V$, Temperature: 25°C
			—	_	±30	LSb	$\Delta VREF \ge 5.0V$, Temperature: $\ge 85^{\circ}C$, -40°C
A07	Egn	Gain Error		_	±15	LSb	$\Delta VREF \ge 5.0V$
A10	—	Monotonicity ⁽¹⁾		-			$V\text{SS} \leq V\text{AIN} \leq V\text{REF}$
A20	$\Delta VREF$	Reference Voltage Range (VREFH – VREFL)	3		AVDD – AVSS	V	
A21	Vrefh	Reference Voltage High	AVss + 3.0V	_	AVDD + 0.3V	V	
A22	Vrefl	Reference Voltage Low	AVss-0.3V	_	AVDD - 3.0V	V	
A25	VAIN	Analog Input Voltage	Vrefl	_	Vrefh	V	

TABLE 3: A/D CONVERTER CHARACTERISTICS

Note 1: The A/D conversion result never decreases with an increase in the input voltage.

A1	B1	B 3	B5	C1	С3	C5	C6	
	Х	Х	Х	Х	Х	Х	Х	

2. Module: Ports

The input leakage will not match the D060 specification in the data sheet. The leakage will meet the 200 nA specification at TA = 25°C. At TA = 85°C, the leakage will be up to a maximum of 2 μ A.

Work around

None.

Affected Silicon Revisions

A1	B1	B 3	B5	C1	С3	C5	C6	
Х		Х	Х	Х	Х	Х	Х	

3. Module: High/Low-Voltage Detect (HLVD)

The high-to-low (VDIRMAG = 0) setting of the HLVD may send initial interrupts. High trip points that are close to the intended operating voltage are susceptible to this behavior.

Work around

Select a lower trip voltage that allows consistent start-up or clear any initial interrupts from the HLVD on start-up.

Affected Silicon Revisions

I	A1	B1	B 3	B5	C1	С3	C5	C6	
	Х	Х	Х	Х	Х	Х	Х	Х	

4. Module: ECCP

The tri-state setting of the auto-shutdown feature in the enhanced PWM will not successfully drive the pin to tri-state. The pin will remain an output and should not be driven externally. All tri-state settings will be affected.

Work around

Use one of the other two auto-shutdown states available, as outlined in the data sheet.

Affected Silicon Revisions

A1	B1	B 3	B5	C 1	C3	C5	C6	
Х	Х	Х	Х	Х	Х	Х	Х	

5. Module: EUSART

In Synchronous Transmit mode, data may be corrupted if using the TXxIF bit to determine when to load the TXREGx register. One or more of the intended transmit messages may be incorrect.

Work around

A fixed delay added before loading the TXREGx may not be a reliable work around. When loading the TXREGx, check that the TRMT bit inside of the TXSTAx register is set instead of checking the TXxIF bit. The following code can be used:

EXAMPLE 1: EUSART SYNCHRONOUS TRANSMIT WORK AROUND

while(!TXSTAxbits.TRMT);

// wait to load TXREGx until TRMT is set

A1								
Х	Х	Х	Х	Х	Х	Х	Х	

6. Module: IPD and IDD

The IPD and IDD limits will not match the data sheet. The values in bold in Section 31.2 "DC Characteristics: Power-Down and Supply Current PIC18F87K90 Family (Industrial)" reflect the updated silicon maximum limits.

31.2 DC Characteristics: Power-Down and Supply Current PIC18F87K90 Family (Industrial)

PIC18F8 (Industri	37K90 Family al)				ons (unless ot C ≤ TA ≤ +85°C	herwise stated) for industrial		
Param. No.	Device	Тур.	Max.	Units		Conditions		
	Power-Down C	urrent (IPD) Sleep Mo	ode				
	PIC18FXXK90	10	500	nA	-40°C			
		20	500	nA	+25°C	VDD	0 = 1.8V,	
		120	600	nA	+60°C	Regulat	tor Disabled	
		630	2000	nA	+85°C			
	PIC18FXXK90	50	700	nA	-40°C			
		60	900	nA	+25°C	VDD	0 = 3.3V,	
		170	1100	nA	+60°C	Regulat	tor Disabled	
		700	5000	nA	+85°C			
	PIC18FXXK90	350	1300	nA	-40°C			
		400	1400	nA	+25°C	VD	d = 5V,	
		550	1500	nA	+60°C	Regula	tor Enabled	
		1350	4000	nA	+85°C			
	Supply Current	t (IDD)						
	PIC18FXXK90	3.7	8.5	μA	-40°C			
		5.4	10	μA	+25°C	VDD = 1.8V, Regulator Disabled		
		6.60	13	μA	+85°C			
	PIC18FXXK90	8.7	18	μA	-40°C		Fosc = 32 kHz,	
		10	20	μA	+25°C	VDD = 3.3V, Regulator Disabled	(SEC_RUN mode,	
		12	35	μA	+85°C		SOSCSEL = 01)	
	PIC18FXXK90	60	150	μA	-40°C			
		90	190	μA	+25°C	VDD = 5V, Regulator Enabled		
		100	240	μA	+85°C			
	PIC18FXXK90	1.2	4	μA	-40°C			
		1.7	5	μA	+25°C	VDD = 1.8V, Regulator Disabled		
		2.6	6	μA	+85°C			
	PIC18FXXK90	1.6	7	μA	-40°C)/== 0.0)/	Fosc = 32 kHz,	
		2.8	9	μA	+25°C	VDD = 3.3V, Regulator Disabled	(SEC_IDLE mode,	
		4.1	17	μA	+85°C		SOSCSEL = 01)	
	PIC18FXXK90	60	160	μA	-40°C			
		80	180	μA	+25°C	VDD = 5V, Regulator Enabled		
		100	240	μA	+85°C			

Work around

None.

Affected Silicon Revisions

A1	B1	B 3	B5	C1	С3	C5	C6	
Х								

7. Module: Ultra Low-Power Sleep

7.1 Entering Ultra Low-Power Sleep mode, by setting RETEN = 0 and SRETEN = 1, will cause the part not to be programmable through ICSP™. This issue occurs when the RETEN fuse bit in CONFIG1L<0> is cleared to '0', the SRETEN bit in the WDTCON register is set to '1' and a SLEEP instruction is executed within the first 350 µs of code execution, or whenever the above Sleep mode is entered and MCLR is disabled. Discontinue use of the MCLR disabled RG5 mode if ICSP reprogramming is necessary.

Work around

Use normal Sleep and Low-Power Sleep modes only, or on any Reset, ensure at least 350 µs passes before executing a SLEEP instruction when ULP is enabled. To ensure the Ultra Low-Power Sleep mode is not enabled, the RETEN fuse bit in CONFIG1L<0> should be set to a '1', and the SRETEN bit in the WDTCON register should be cleared to a '0'. The following code can be used:

EXAMPLE 2: ULTRA LOW-POWER SLEEP WORK AROUND

//This will ensure the RETEN fuse is set to $\ensuremath{1}$	
#pragma config RETEN = OFF	
//This will ensure the SRETEN bit is $\ensuremath{0}$	
WDTCONbits.SRETEN = 0;	

If the Ultra Low-Power Sleep mode is needed, then the user must ensure that the minimum time, before the first SLEEP instruction is executed, is greater than $350 \ \mu s$.

Affected Silicon Revisions

A1	B1	B 3	B5	C1	С3	C5	C6	
Х	Х			Х				

7.2 Using the WDT to exit Ultra Low-Power Sleep mode when VDD>4.5V can cause the part to enter a Reset state that requires a POR to exit. The issue occurs when the RETEN fuse bit in CONFIG1L<0> is cleared to '0', the SRETEN bit in the WDTCON register is set to '1', VDD>4.5V. Upon entering the <u>failure</u> state, the device ceases to respond to MCLR events and will only exit the Reset state upon experiencing a POR.

Work around

Do not use the Ultra Low-Power Sleep mode with VDD above 4.5V.

A3	B1	B3	B5	C1	С3	C5	C6	
Х	Х	Х	Х	Х	Х	Х	Х	

8. Module: Resets (BOR)

An unexpected Reset may occur if the Brown-out Reset module (BOR) is disabled, and then re-enabled, when the High/Low-Voltage Detection (HLVD) module is not enabled (HLVDCON < 4 > = 0). This issue affects BOR BOREN<1:0> modes: 10 and = BOREN<1:0> = 01. In both of these modes, if the BOR module is re-enabled while the device is active, unexpected Resets may be generated.

Work around

If BOR is required, and power consumption is not an issue, use BOREN<1:0> = 11. For BOREN<1:0> = 10 mode, either switch to BOREN<1:0> = 11 mode or enable the HLVD (HLVDCON<4> = 1) prior to entering Sleep. If power consumption is an issue and low power is desired, do not use BOREN<1:0> = 10 mode. Instead, use BOREN<1:0> = 01 and follow the steps below when entering and exiting Sleep.

 Disable BOR by clearing SBOREN (RCON<6> = 0).

WDTCONbits.SBOREN = 0;

2. Enter Sleep mode (if desired).

Sleep();

 After exiting Sleep mode (if entered), enable the HLVD (HLVDCON<4> = 1).

HLVDCONbits.HLVDEN = 1;

 Wait for the internal reference voltage (TIRVST) to stabilize (typically 25 us).

while(!HLVDCONbits.IRVST);

5. Re-enable BOR by setting SBOREN (RCON<6> = 1).

WDTCONbits.SBOREN = 1;

6. Disable the HLVD by clearing HLVDEN (HLVDCON<4> = 0).

HLVDCONbits.HLVDEN = 0;

Affected Silicon Revisions

I	A1	B1	B 3	B5	C1	С3	C5	C6	
I	Х	Х	Х	Х	Х	Х	Х	Х	

9. Module: RG5 Pin

RG5 will cause excess pin leakage whenever it is driven low. When RG5 is held at 0V, the pin will typically source an additional 160 μA of current.

Work around

In power-sensitive applications, using RG5 as an input, ensure that any input attached to this pin Idles high.

Affected Silicon Revisions

A1	B1	B3	B5	C1	С3	C5	C6	
	Х							

10. Module: Primary Oscillator (XT Mode)

On some parts, using the XT oscillator at the top end of its specified frequency range (3.0-4.0 MHz) may cause the part to cease driving the oscillator.

Work around

Use XT mode only for frequencies lower than 3.0 $\ensuremath{\mathsf{MHz}}$.

Use HS mode if frequencies greater than 3.0 MHz on a crystal oscillator are required.

A1	B1	B 3	B5	C1	C3	C5	C6	
Х	Х	Х		Х	Х			

11. Module: Timer1/3/5/7

When Timer1, Timer3, Timer5 or Tmer7 is operated in Asynchronous External Input mode, unexpected interrupt flag generation may occur if an external clock edge arrives too soon following a firmware write to the TMRxH:TMRxL registers. An unexpected interrupt flag event may also occur when enabling the module or switching from Synchronous to Asynchronous mode.

Work around

This issue only applies when operating the timer in Asynchronous mode. Whenever possible, operate the timer module in Synchronous mode to avoid spurious timer interrupts.

If Asynchronous mode must be used in the application, potential strategies to mitigate the issue may include any of the following:

- Design the firmware so it does not rely on the TMRxIF flag or keep the respective interrupt disabled. The timer still counts normally and does not reset to 0x0000 when the spurious interrupt flag event is generated.
- Design the firmware so that it does not write to the TMRxH:TMRxL registers or does not periodically disable/enable the timer, or switch modes. Reading from the timer does not trigger the spurious interrupt flag events.
- If the firmware must use the timer interrupts and must write to the timer (or disable/enable, or mode switch the timer), implement code to suppress the spurious interrupt event, should it occur. This can be achieved by following the process shown in Example 3.

EXAMPLE 3: ASYNCHRONOUS TIMER MODE WORK AROUND TO AVOID SPURIOUS INTERRUPT

//Timerl update procedure in asynchronous mode										
//The code below uses Timer1	as example									
T1CONbits.TMR1ON = 0;	//Stop timer from incrementing									
PIE1bits.TMR1IE = 0;	//Temporarily disable Timer1 interrupt vectoring									
$TMR1H = 0 \times 00;$	//Update timer value									
$\text{TMR1L} = 0 \times 00;$										
<pre>ICONbits.TMRION = 1; //Turn on timer</pre>										
//Now wait at least two full T1CKI periods + $2T_{CY}$ before re-enabling Timer1 interrupts.										
//Depending upon clock edge t	iming relative to TMR1H/TMR1L firmware write operation,									
//a spurious TMR1IF flag even	t may sometimes assert. If this happens, to suppress									
//the actual interrupt vector	ing, the TMR1IE bit should be kept clear until									
//after the "window of opport	unity" (for the spurious interrupt flag event has passed).									
//After the window is passed,	no further spurious interrupts occur, at least									
//until the next timer write	(or mode switch/enable event).									
while(TMR1L < 0x02);	//Wait for 2 timer increments more than the Updated Timer									
	//value (indicating more than 2 full T1CKI clock periods elapsed)									
NOP();	//Wait two more instruction cycles									
NOP();										
PIR1bits.TMR1IF = 0;	//Clear TMR1IF flag, in case it was spuriously set									
PIElbits.TMR1IE = 1;	//Now re-enable interrupt vectoring for timer 1									

A1	B1	B3	B5	C1	C3	C5	C6	
Х	Х	Х		Х	Х	Х		

Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS39957**D**):

Note:	Corrections are shown in bold . Where								
	possible, the original bold text formatting								
	has been removed for clarity.								

1. Module: Electrical Characteristics

 Table 31-25 A/D Converter Characteristics has

 been corrected. The changes are shown in bold

 in the table below:

TABLE 31-25: A/D CONVERTER CHARACTERISTICS: PIC18F87K90 FAMILY (INDUSTRIAL)

Param. No.	Sym.	Characteristic	Min.	Тур.	Max.	Units	Conditions
A01	Nr	Resolution			12	bit	$\Delta V \text{Ref} \geq 5.0 V$
A03	Eı∟	Integral Linearity Error	—	±1	±6.0	LSB	$\Delta \text{VREF} \geq 5.0 \text{V}$
A04	Edl	Differential Linearity Error	—	±1	+3.0/-1.0	LSB	$\Delta \text{VREF} \geq 5.0 \text{V}$
A06	EOFF	Offset Error	—	±1	±18.0	LSB	$\Delta \text{VREF} \geq 5.0 \text{V}$
A07	Egn	Gain Error	_	±1	±8.0	LSB	$\Delta \text{VREF} \geq 5.0 \text{V}$
A10		Monotonicity ⁽¹⁾	_		_		$V\text{SS} \leq V\text{AIN} \leq V\text{REF}$
A20	$\Delta VREF$	Reference Voltage Range (VREFH – VREFL)	3	_	Vdd - Vss	V	
A21	Vrefh	Reference Voltage High	Vss + 3.0V		VDD + 0.3V	V	
A22	VREFL	Reference Voltage Low	Vss-0.3V		Vdd - 3.0V	V	
A25	VAIN	Analog Input Voltage	VREFL		Vrefh	V	
A30	ZAIN	Recommended Impedance of Analog Voltage Source	—		2.5	kΩ	
A50	IREF	VREF Input Current ⁽²⁾	—		5 150	μΑ μΑ	During VAIN acquisition. During A/D conversion cycle.

Note 1: The A/D conversion result never decreases with an increase in the input voltage.

2: VREFH current is from the RA3/AN3/VREF+ pin or VDD, whichever is selected as the VREFH source. VREFL current is from the RA2/AN2/VREF-/CVREF pin or VSS, whichever is selected as the VREFL source.

2. Module: Voltage Regulator Pins (ENVREG and VCAP/VDDCORE)

In Section 2.4 "Voltage Regulator Pins (ENVREG and VCAP/VDDCORE)", the description of the Regulator Disabled mode has changed. The changes are shown in **bold** below:

When the regulator is disabled, the VCAP/ VDDCORE pin must only be tied to a $0.1 \, \mu F$ capacitor. Refer to Section 31.0 "Electrical Characteristics" for information on VDD and VDDCORE.

3. Module: DC Characteristics (Injection Current)

The following table of specifications for current injected into the microcontroller will be added to **Section 31.0 "Electrical Characteristics"**.

31.4 DC Characteristics: PIC18F87K90 Family (Industrial)

DC CHA	RACTERIS	$\begin{array}{l} \mbox{Standard Operating Conditions: } 1.8V \ to \ 5.5V \\ \mbox{Operating temperature} & -40^\circ C \leq TA \leq +85^\circ C \ for \ Industrial \\ -40^\circ C \leq TA \leq +125^\circ C \ for \ Extended \end{array}$					
Param. No.	Symbol	Characteristic	Min.	Тур.	Max.	Units	Conditions
D160a	licl	Input Low Injection Current	0	_	₋₅ (1)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO
D160b	ІІСН	Input High Injection Current	0	—	+5 ⁽¹⁾	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO
D160c	D160c ∑lic⊤ Total Input Injection Current (sum of all I/O and control pins)		-20 ^(1,2)	_	+20 ^(1,2)	mA	Absolute instantaneous sum of all input injection currents from all I/O pins $($ IICL + $ $ IICH $) \leq \sum$ IICT

Note 1: Injection currents > | 0 | can affect the A/D results.

2: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted.

4. Module: DC Characteristics (Input Low Voltage and Input High Voltage)

Input Low Voltage and Input High Voltage have been corrected. The changes are shown in bold in the table below:

31.3 DC Characteristics: PIC18F87K90 Family (Industrial/Extended)

DC CHA	RACTER	ISTICS			Conditions re-40°C ≤ TA		s otherwise stated) °C
Param. No.	Symbol	Characteristic	Min.	Typ.†	Max.	Units	Conditions
	VIL	Input Low Voltage					
		I/O PORT:					
D030		with TTL buffer	—	_	0.8	V	$\textbf{4.5V} \leq \textbf{V} \textbf{D} \textbf{D} \leq \textbf{5.5V}$
D030A				_	0.15 VDD	V	$V\text{dd} \leq 4.5 V$
D031		with Schmitt Trigger buffer		_	0.2 Vdd	V	
		with I ² C levels	_	_	0.3 VDD	V	
		with SMBus levels	—	_	0.8	V	$\textbf{2.7V} \leq \textbf{VDD} \leq \textbf{5.5V}$
D032		MCLR	—	_	0.2 Vdd	V	
D033		OSC1	—	—	0.2 Vdd	V	
D034		SOSCI	—	—	0.3 Vdd	V	
	Viн	Input High Voltage					
		I/O ports:					
D040		with TTL buffer	2.0	_	—	V	$4.5V \le V\text{DD} \le 5.5V$
			0.25 Vdd	_	—	V	$\textbf{1.8V} \leq V \text{DD} \leq 4.5 \text{V}$
D041		with Schmitt Trigger buffer	0.8 Vdd	_	—	V	$\textbf{2.0V} \leq \textbf{VDD} \leq \textbf{5.5V}$
		with I ² C levels	0.7 Vdd	_	—	V	
		with SMBus levels	2.1	_	—	V	$\textbf{2.7V} \leq \textbf{VDD} \leq \textbf{5.5V}$
D042		MCLR	0.8 Vdd	_	_	V	
D043		OSC1 (HS mode)	0.7 Vdd	_	_	V	
D043A		OSC1 (EC/ECPLL mode)	0.8 Vdd	_	_	V	
D044		SOSCI	0.7 Vdd	_	—	V	

5. Module: I/O Ports

Text in section 11.2 and 11.7 is corrected. Also, Example 11-1, 11-6 and Table 11-2 are corrected accordingly. The changes are shown in bold.

11.2 PORTA, TRISA and LATA Registers

PORTA is an 8-bit wide, bidirectional port. The corresponding Data Direction and Output Latch registers are TRISA and LATA.

RA4/T0CKI is a Schmitt Trigger input. All other PORTA pins have TTL input levels and full CMOS output drivers.

The RA4 pin is multiplexed with the Timer0 clock input and one of the LCD segment drives. RA5 and RA<3:0> are multiplexed with analog inputs for the A/D Converter. RA1 is multiplexed with analog as well as the LCD segment drive.

The operation of the analog inputs as A/D Converter inputs is selected by clearing or setting the ANSEL<3:0> control bits in the **ANCON0** register. The corresponding TRISA bits control the direction of these pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

11.7 PORTF, LATF and TRISF Registers

PORTF is a 7-bit wide, bidirectional port. The corresponding Data Direction and Output Latch registers are TRISF and LATF. All pins on PORTF are implemented with Schmitt Trigger input buffers. Each pin is individually configurable as an input or output.

PORTF is multiplexed with analog peripheral functions, as well as LCD segments. Pins, RF1 through RF6, may be used as comparator inputs or outputs by setting the appropriate bits in the CMCON register. To use RF<7:1> as digital inputs, it is also necessary to turn off the comparators.

Note 1:	On device Resets, pins, RF<7:1>, are
	configured as analog inputs and are read
	as '0'.

2: To configure PORTF as a digital I/O, turn off the comparators and clear ANCON0 and ANCON1 to digital.

EXAMPLE 11-1: INITIALIZING PORTA

CLRF	PORTA	;	Initialize PORTA by
		;	clearing output latches
CLRF	LATA	;	Alternate method to
		;	clear output data latches
BANKSEL	ANCON1		
MOVLW	00h	;	Configure PORTA
MOVWF	ANCON0	;	as digital port
MOVLW	BFh	;	Value used to initialize
		;	data direction
MOVWF	TRISA	;	Set RA<7, 5:0> as inputs,
		;	RA<6> as output

EXAMPLE 11-6: INITIALIZING PORTF

CLRF	PORTF	<pre>; Initialize PORTF by ; clearing output ; data latches</pre>
CLRF	LATF	; Alternate method
		; to clear output
		; data latches
BANKSEL	ANCON0	
MOVLW	1Fh	; Make AN6, AN7 and AN5 digital
MOVWF	ANCON0;	
MOVLW	F0h	; Make AN8, AN9, AN10 and AN11
		digital
MOVWF	ANCON1;	Set PORTF as digital I/O
MOVLW	CEh	; Value used to
		; initialize data
		; direction
MOVWF	TRISF	; Set RF3:RF1 as inputs
		; RF5:RF4 as outputs
		; RF7:RF6 as inputs

TABLE 11-2:	SUMMARY OF REGISTERS ASSOCIATED WITH PORTA
-------------	--

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
PORTA	RA7 ⁽¹⁾	RA6 ⁽¹⁾	RA5	RA4	RA3	RA2	RA1	RA0	78
LATA	LATA7 ⁽¹⁾	LATA6 ⁽¹⁾	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0	78
TRISA	TRISA7 ⁽¹⁾	TRISA6 ⁽¹⁾	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	78
ANCON0	ANSEL7	ANSEL6	ANSEL5	ANSEL4	ANSEL3	ANSEL2	ANSEL1	ANSEL0	81
LCDSE1	SE15	SE14	SE13	SE12	SE11	SE10	SE09	SE08	83
LCDSE2	SE23	SE22	SE21	SE20	SE19	SE18	SE17	SE16	83

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PORTA.

Note 1: These bits are enabled depending on the oscillator mode selected. When not enabled as PORTA pins, they are disabled and read as 'x'.

6. Module: Oscillator Configurations

The following section should be included in the oscillator section of the data sheet, directly underneath Section 3.6.4.3 "Compensating with the CCP Module in Capture Mode".

3.6.5 LFINTOSC OPERATION IN SLEEP

When the Watchdog Timer (WDT) or Real-Time Clock and Calendar (RTCC) modules are enabled and configured to use the LFINTOSC, the LFINTOSC will continue to run when the device is in Sleep, unlike other internal clock sources.

While in Sleep, the LFINTOSC has two power modes, a High-Power and a Low-Power mode, controlled by the INTOSCSEL bit in the CONFIG1L Configuration Word. The High-Power mode is the same as the LFINTOSC while the part is awake and conforms to the specifications outlined for that oscillator. The Low-Power mode consumes less current, but has a much lower accuracy and is not recommended for timing-sensitive applications.

7. Module: DC Characteristics (Comparator Specifications)

Parameter D303, Comparator Response Time is incorrect, the correct specifications are as follows:

TABLE 31-2: COMPARATOR SPECIFICATIONS

Operating Conditions: $1.8V \le VDD \le 5V$, $-40^{\circ}C \le TA \le +125^{\circ}C$ (unless otherwise stated)								
Param. No.	Sym.	Characteristics	Min.	Тур.	Max.	Units	Comments	
D300	VIOFF	Input Offset Voltage	—	±5.0	40	mV		
D301	VICM	Input Common-Mode Voltage	—	—	AVDD - 1.5	V		
D302	CMRR	Common-Mode Rejection Ratio	55	—		dB		
D303	TRESP	Response Time ⁽¹⁾	—	675	1200	ns		
D304	Тмс2о∨	Comparator Mode Change to Output Valid*	—	—	10	μS		

Note 1: Response time measured with one comparator input at (AVDD – 1.5)/2, while the other input transitions from Vss to VDD.

PIC18F87K90 FAMILY

APPENDIX A: DOCUMENT REVISION HISTORY

Rev A Document (5/2010)

Initial release of this document. Silicon issues 1 (A/D), 2 (BOR), 3 (HLVD). and 4 (Ports).

Rev B Document (11/2010)

Added data sheet clarifications 1-3 (Voltage Regulator Pins – ENVREG and VCAP/VDDCORE). Removed silicon issue 2 (Brown-out Reset). Changes were made to silicon issue 3 (HLVD). Added silicon issues 4 (ECCP), 5 (EUSART) and 6 (IPD and IDD).

Rev C Document (4/2011)

Added silicon issues 7 (Ultra Low-Power Sleep), 8 (Resets – BOR) and 9 (RG5 Pin). Removed data sheet clarifications 1-3 (Voltage Regulator Pins (ENVREG and VCAP/VDDCORE). Added data sheet clarification 1 (Electrical Characteristics).

Rev D Document (2/2012)

Added data sheet clarification 2 (Voltage Regulator Pins – ENVREG and VCAP/VDDCORE) and 3 (DC Characteristics – Injection Current).

Rev E Document (10/2012)

Added MPLAB X IDE; Added Silicon Revision C3.

Data Sheet Clarifications: Added Module 4, DC Characteristics (Input Low Voltage and Input High Voltage).

Rev F Document (12/2013)

Added silicon issue 1.2 (Analog-to-Digital Converter) and silicon issue 10 (Primary Oscillator – XT Mode); Other minor corrections.

Rev G Document (07/2014)

Added Module 11, Timer1/3/5/7 to Silicon Errata Issues section.

Rev H Document (9/2014)

Added Module 7.2; Other minor corrections.

Rev J Document (9/2014)

Added silicon revision C5.

Rev K Document (01/2015)

Data Sheet Clarifications: Added module 5.

Rev L Document (03/2015)

Added silicon revision C6; Other minor corrections. Data Sheet Clarifications: added module 6.

Rev M Document (07/2015)

Added Silicon Revision B5; Other minor corrections.

Rev N Document (01/2017)

Data Sheet Clarifications: Added Module 7, changed Parameter D303 specifications.

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEEL0Q® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV = ISO/TS 16949=

Trademarks

The Microchip name and logo, the Microchip logo, AnyRate, AVR, AVR logo, AVR Freaks, BeaconThings, BitCloud, CryptoMemory, CryptoRF, dsPIC, FlashFlex, flexPWR, Heldo, JukeBlox, KEELOQ, KEELOQ logo, Kleer, LANCheck, LINK MD, maXStylus, maXTouch, MediaLB, megaAVR, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, Prochip Designer, QTouch, RightTouch, SAM-BA, SpyNIC, SST, SST Logo, SuperFlash, tinyAVR, UNI/O, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

ClockWorks, The Embedded Control Solutions Company, EtherSynch, Hyper Speed Control, HyperLight Load, IntelliMOS, mTouch, Precision Edge, and Quiet-Wire are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, BodyCom, chipKIT, chipKIT logo, CodeGuard, CryptoAuthentication, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, EtherGREEN, In-Circuit Serial Programming, ICSP, Inter-Chip Connectivity, JitterBlocker, KleerNet, KleerNet logo, Mindi, MiWi, motorBench, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PureSilicon, QMatrix, RightTouch logo, REAL ICE, Ripple Blocker, SAM-ICE, Serial Quad I/O, SMART-I.S., SQI, SuperSwitcher, SuperSwitcher II, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2010-2017, Microchip Technology Incorporated, All Rights Reserved.

ISBN: 978-1-5224-1279-3



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://www.microchip.com/ support

Web Address: www.microchip.com

Atlanta Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

Boston Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Dallas Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi, MI Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Indianapolis Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110 Tel: 408-436-4270

Canada - Toronto Tel: 905-695-1980 Fax: 905-695-2078

ASIA/PACIFIC

Asia Pacific Office Suites 3707-14, 37th Floor Tower 6, The Gateway

Harbour City, Kowloon Hong Kong Tel: 852-2943-5100 Fax: 852-2401-3431

Australia - Sydney Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing Tel: 86-10-8569-7000 Fax: 86-10-8528-2104

China - Chengdu Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Dongguan Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

China - Hangzhou Tel: 86-571-8792-8115 Fax: 86-571-8792-8116

China - Hong Kong SAR Tel: 852-2943-5100

China - Nanjing Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

Fax: 852-2401-3431

China - Qingdao Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai Tel: 86-21-3326-8000 Fax: 86-21-3326-8021

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8864-2200 Fax: 86-755-8203-1760

China - Wuhan Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

ASIA/PACIFIC

China - Xiamen Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai Tel: 86-756-3210040 Fax: 86-756-3210049

India - Bangalore Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune Tel: 91-20-3019-1500

Japan - Osaka Tel: 81-6-6152-7160 Fax: 81-6-6152-9310

Japan - Tokyo Tel: 81-3-6880- 3770 Fax: 81-3-6880-3771

Korea - Daegu Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu Tel: 886-3-5778-366 Fax: 886-3-5770-955

Taiwan - Kaohsiung Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen Tel: 45-4450-2828 Fax: 45-4485-2829

Finland - Espoo Tel: 358-9-4520-820

France - Paris Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

France - Saint Cloud Tel: 33-1-30-60-70-00

Germany - Garching Tel: 49-8931-9700 **Germany - Haan** Tel: 49-2129-3766400

Germany - Heilbronn Tel: 49-7131-67-3636

Germany - Karlsruhe Tel: 49-721-625370

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Rosenheim Tel: 49-8031-354-560

Israel - Ra'anana Tel: 972-9-744-7705

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Norway - Trondheim Tel: 47-7289-7561

Poland - Warsaw Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

UK - Wokingham Tel: 44-118-921-5800 Fax: 44-118-921-5820